



IN THE
UNITED STATES PATENT & TRADEMARK OFFICE

APPLICATION OF: Toshihide ITO, et al.
OF: 200335-0037
CASE: 09/671,084
SERIAL NO.:)
FILED ON: September 27, 2000)
FOR: Sn-Ag-Cu SOLDER AND SURFACE)
TREATMENT AND PARTS MOUNTING)
METHODS USING THE SAME)

) EXPRESS MAIL
CERTIFICATE OF
MAILING FOR:
RCE Application

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Dear Sirs:

AUTHORIZATION TO PAY AND PETITION FOR THE ACCEPTANCE OF ANY NECESSARY FEES: If any charges or fees must be paid in connection with the following Communication (including but not limited to the payment of issue fees), they may be paid out of our deposit account No. 50-1965. If this payment also requires a Petition, please construe this authorization to pay as the necessary Petition which is required to accompany the payment.

INFORMATION DISCLOSURE STATEMENT

Applicant submits herewith a list of prior art (PTO form 1449) which should be placed of record in the above identified application.

It is believed that the present invention clearly distinguishes over the enclosed prior art.

Dated: 09/02

By: 

J. Warren Whitesel, Reg. No. 16830
Michael Best & Friedrich LLC
401 N. Michigan Ave., Suite 1900
Chicago, IL 60611
Tel: 312-661-2100; Fax: 312-661-0029
Attorneys for Applicant

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Date of Deposit: August 9, 2002

I hereby certify that the above listed papers or fees are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above, addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231. The person mailing these papers/fees is:

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